

DESCRIPTION

The high power HVV0912-450 device is a high voltage silicon enhancement mode RF transistor designed for L-band pulsed avionics applications operating over the frequency range of 960 MHz and 1215 MHz.

FEATURES

High Power Gain
Excellent Ruggedness
50V Supply Voltage

ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Value	Unit
V_{DSS}	Drain-Source Voltage	95	V
V_{GS}	Gate-Source Voltage	-10 to +10	V
I_{DSX}	Drain Current	40	A
P_D^2	Power Dissipation	1500	W
T_S	Storage Temperature	-65 to +150	°C
T_J	Junction Temperature	200	°C

THERMAL CHARACTERISTICS

Symbol	Parameter	Max	Unit
θ_{JC}^1	Thermal Resistance	0.05	°C/W

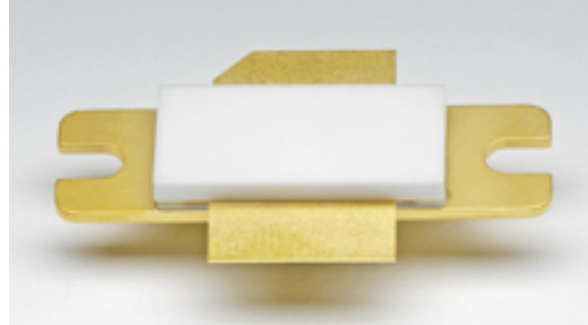
ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Conditions	Typ	Units
$V_{BR(DSS)}$	Drain-Source Breakdown	$V_{GS}=0V, I_D=10mA$	102	V
I_{DSS}	Drain Leakage Current	$V_{GS}=0V, V_{DS}=50V$	<500	µA
I_{GSS}	Gate Leakage Current	$V_{GS}=5V, V_{DS}=0V$	<10	µA
G_p^1	Power Gain	$P_{OUT}=450W, F=960\text{ MHz}$	16.0	dB
IRL^1	Input Return Loss	$P_{OUT}=450W, F=960\text{ MHz}$	7.5	dB
η_D^1	Drain Efficiency	$P_{OUT}=450W, F=960\text{ MHz}$	50	%
PD^1	Pulse Droop	$P_{OUT}=450W, F=960\text{ MHz}$	<0.25	dB

¹Under Pulse Conditions: Pulse Width = 10µs, Pulse Period = 100µs at $V_{DD} = 50V, I_{DQ} = 100mA$

²Rated at $T_{CASE} = 25^\circ C$

PACKAGE



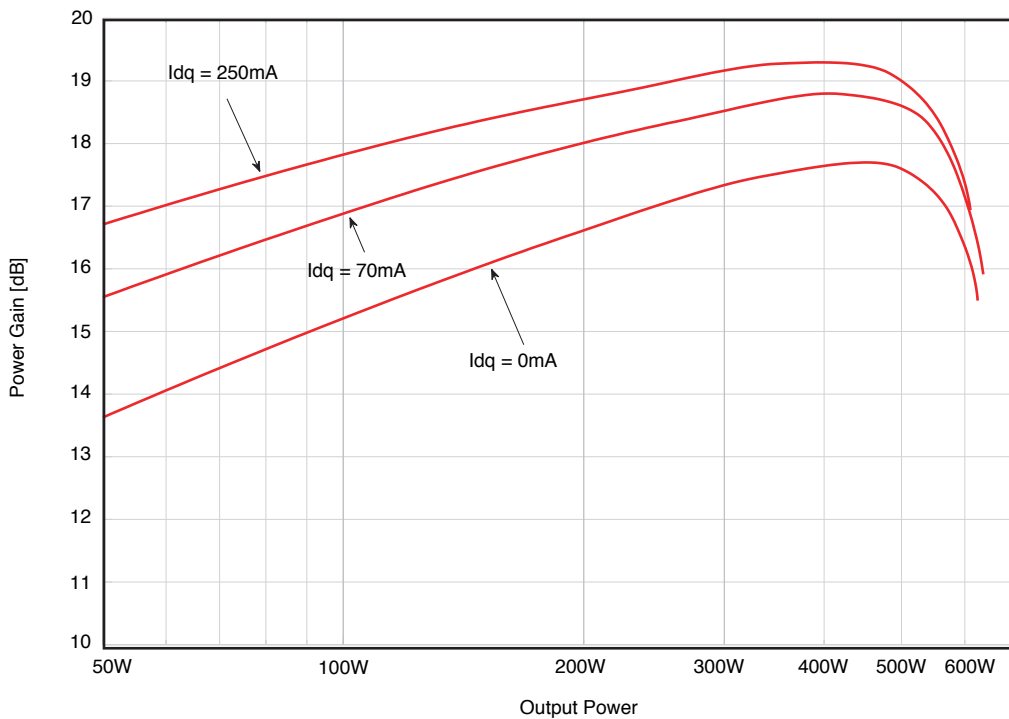
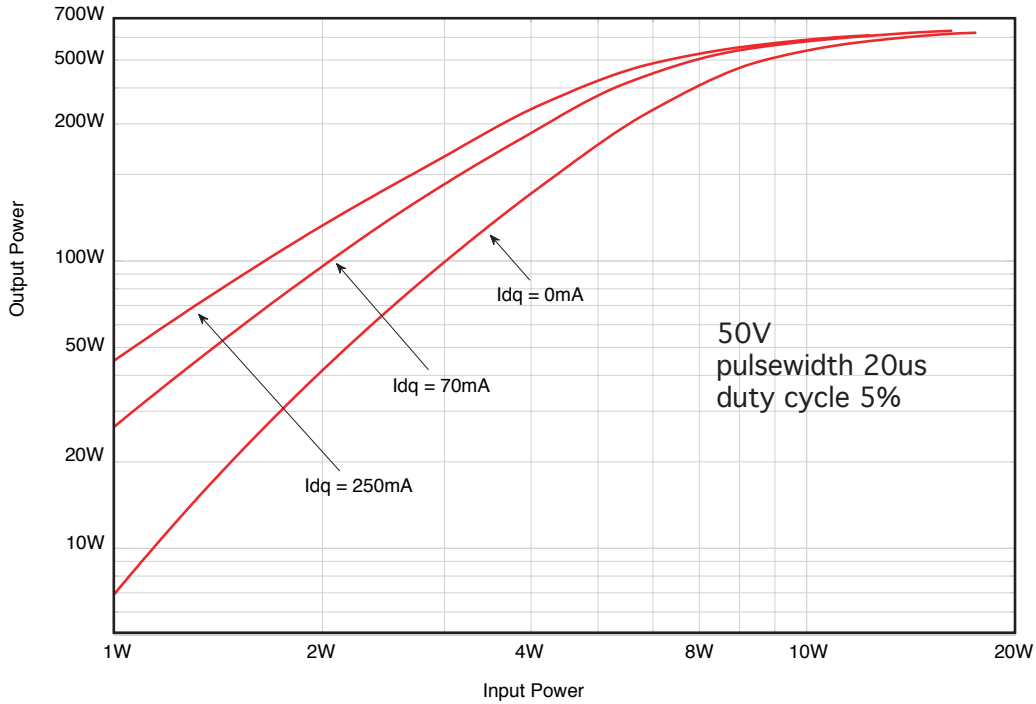
The device utilizes a RoHS compliant flanged package with a ceramic lid. The HV800 package style is qualified for gross leak test – MIL-STD-883, Method 1014.

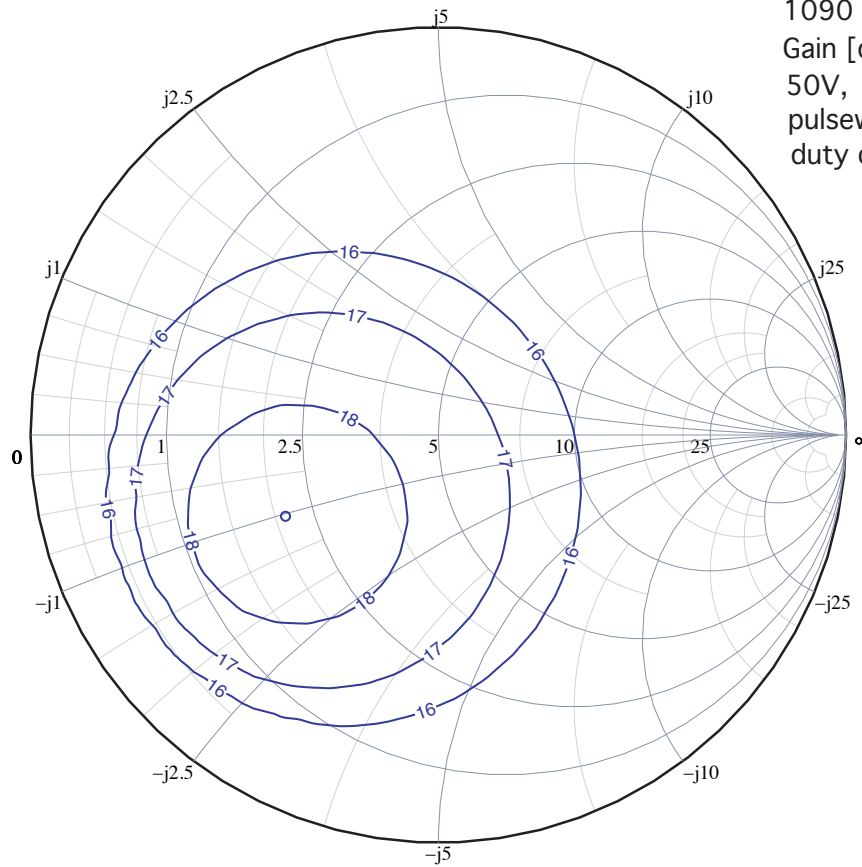
RUGGEDNESS

The HVV0912-450 device is capable of withstanding an output load mismatch corresponding to a 20:1 VSWR at rated output power over all phase angles and operating voltage across the frequency band of operation.

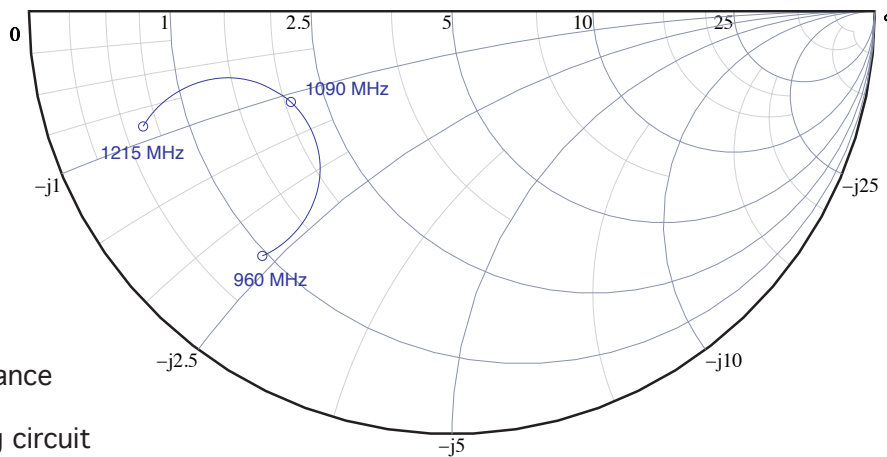
Symbol	Parameter	Test Condition	Max	Units
LMT^1	Load Mismatch Tolerance	$P_{OUT} = 450W$ $F = 960\text{ MHz}$	20:1	VSWR

RF Performance at 1090 MHz



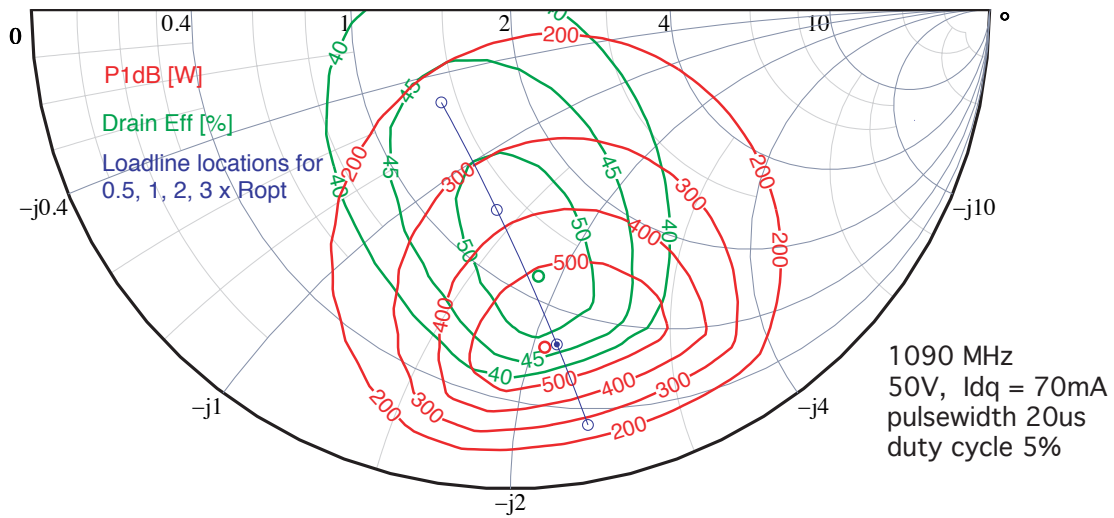
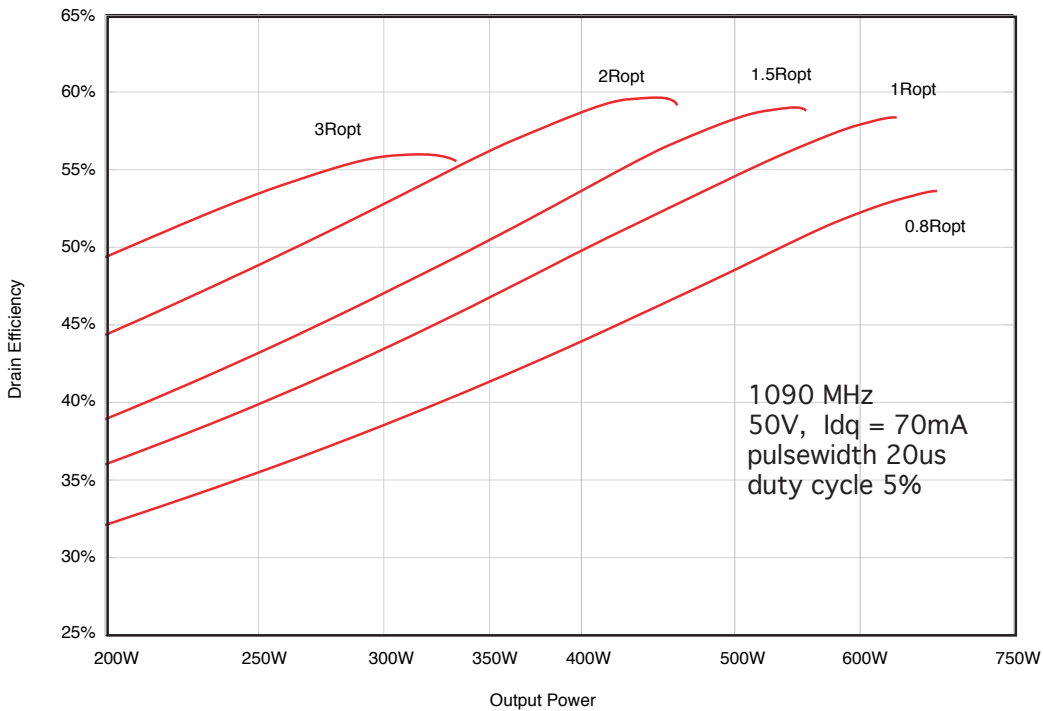


Impedance presented to the input of the device & associated RF Gain performance



Desired impedance targets of the input matching circuit

Drain Efficiency vs P_{out}



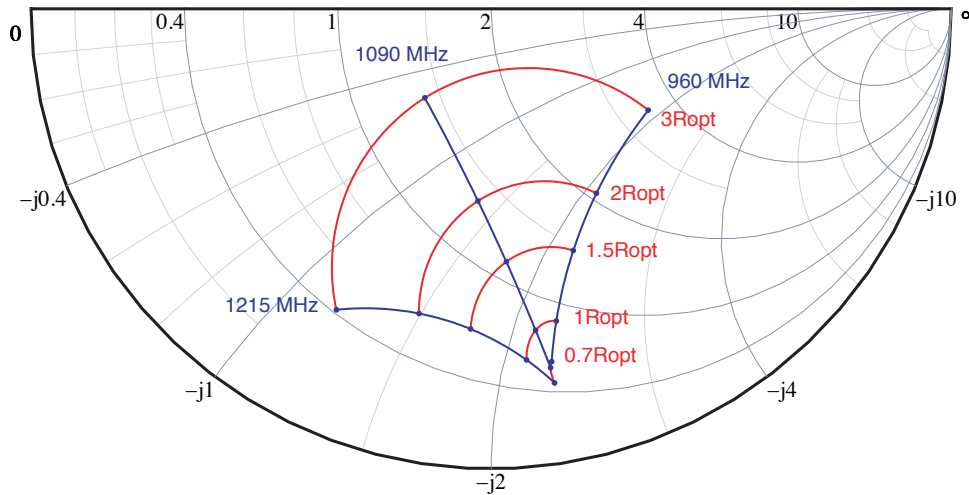
Impedance presented to the output of the device & associated RF output power & Eff performance

Impedance Target Selection

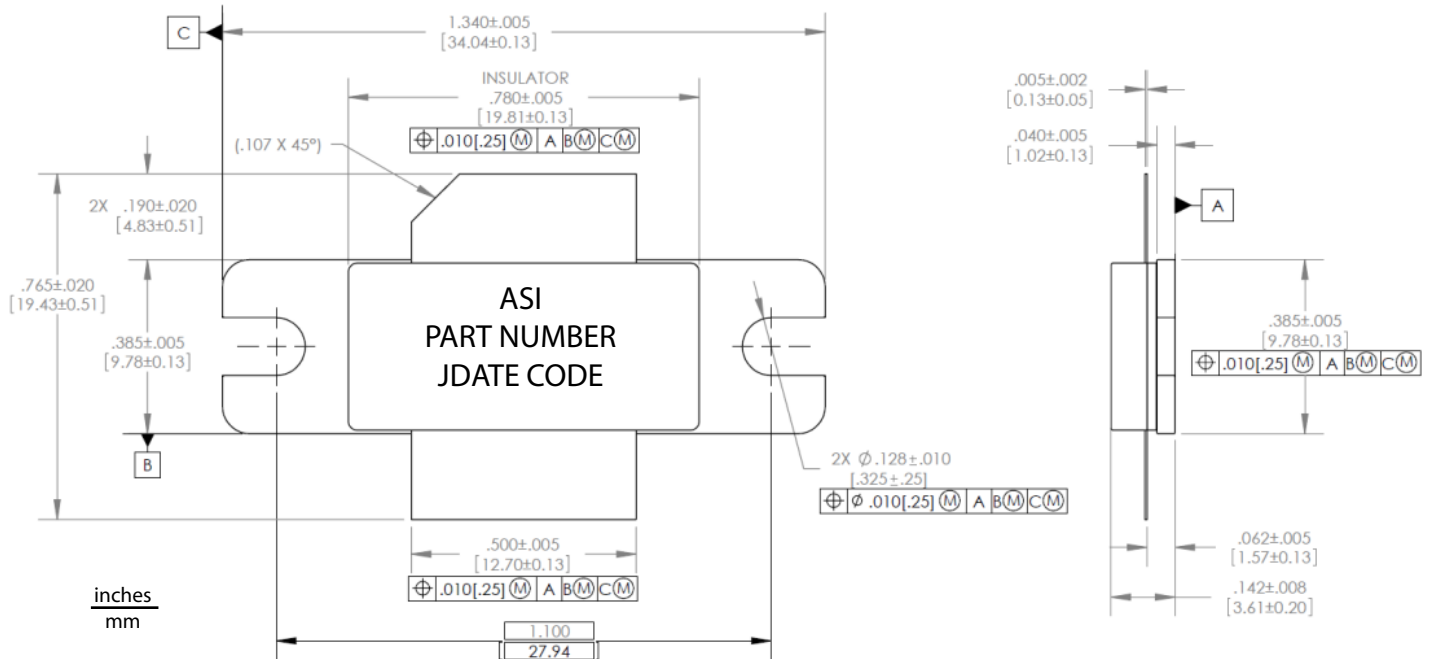
Table of loadline values preselected for best efficiency
Refer to impedance targets below based on the selected
loadline value of R_{opt}

50V **0mA** 70mA 200mA

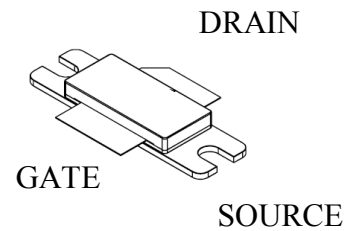
P_{out}	P_{in} 5W	8W	10W	12W	16W
600W			1 R_{opt} 60%	1 R_{opt} 55%	1 R_{opt} 55%
550W		1 R_{opt} 55%	1 R_{opt} 55%	1.5 R_{opt} 60%	1.5 R_{opt} 60%
500W		1 R_{opt} 55%	1.7 R_{opt} 60%	1.7 R_{opt} 60%	
450W	1.5 R_{opt} 55%	1.5 R_{opt} 55%	2 R_{opt} 55%	2 R_{opt} 60%	
400W		2 R_{opt} 55%	2 R_{opt} 60%	2.5 R_{opt} 55%	
350W		2 R_{opt} 55%	1.7 R_{opt} 55%		



PACKAGE DIMENSIONS



Note: Drawing is not actual size.



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